

Abstract**Integrated micro electromechanical system encapsulation component and fabrication process of the component**

The component comprises micro electromechanical systems integrated in a cavity of a substrate and a cover sealed onto the substrate and designed to make the cavity hermetic. The cover comprises at least one groove passing through the cover and defining a central zone completely covering the cavity and a peripheral zone in the cover. A sealing material is deposited at least at the bottom of the groove. Fabrication of the component can comprise a first stage of making at least one groove in the cover, a second stage of bringing the substrate and cover into contact, and a third stage of sealing by depositing a sealing material in the bottom of the groove.